

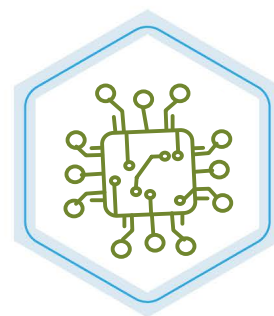
# **DAXin**

**A Materials Design House And More**





- About Daxin 03
- Research and development 04



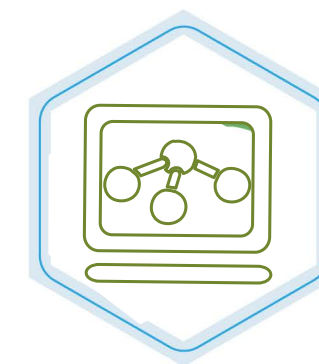
## Products

### Semiconductor Materials

- Photosensitive Dielectric/Passivation
  - Dielectric for Redistribution Layer 05
  - Buffer Layer 06
- Laser Release Layer
  - Multi-functional Release Layer 07
  - Release Layer for Transfer Bonding 08
- Protection Materials
  - Temporary Protection Layer 09
  - Taping protection layer 10
  - Passivation Layer 11
- High-Purity Specialty Chemicals for Wet Clean Process
  - Strippers 12
  - Removers 13
  - Selective Etchants 13
- High-Purity Specialty Chemicals for Nanolithography Process
  - High-Purity Solvent 14
  - Topcoat 14



**DAXiN** Design House for Chemical Materials



### Display Materials

- LCD Materials
  - Black Matrix Resist 15
  - Photo Spacer 16
  - PI Alignment Layer PSA-mode 17
  - PI Alignment Layer FFS-mode 18
  - Thermal Overcoat 19
  - Cu/Mo Etchant 20
  - Photoresist Stripper 20
- Touch Panel Materials
  - Photo Overcoat 21
  - Optical Clear Resin 22
- Flexible EPD/OLED Materials
  - Photosensitive Dielectric / Passivation 23
- MicroLED Materials
  - Bank Materials 24

### Key Raw Materials

- Functional Monomer
  - Dianhydride 25
  - Monoacrylate 26
- Specialty Polymer
  - Modified Acrylate 27
  - Modified Siloxane 28
  - High-Purity Polymer 28

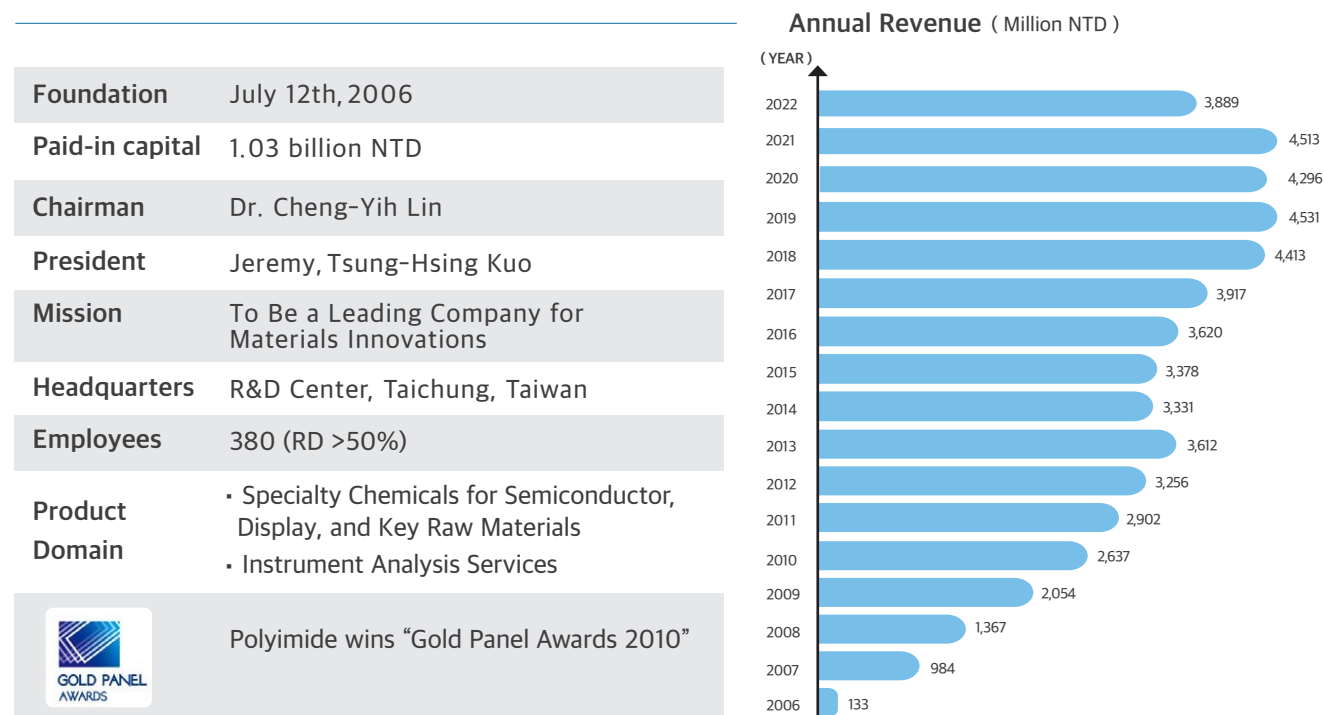
### Instrument Analysis

29

## About DAXIN

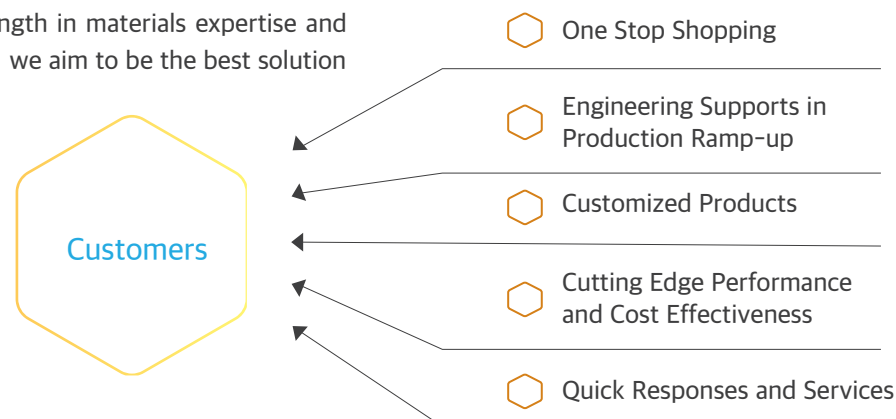
Daxin Materials Corporation is a design house for chemical materials. We develop customized products including specialty chemicals for semiconductor, display, and key raw materials. With our value in fundamental knowledge, diverse talents, and expertise in materials design, equipment technology and process development, we provide innovative and value-added solutions for our customers.

Founded in 2006, Daxin is continuously pursuing innovation, ambition and sustainability, aiming to become an advanced foundry for materials innovations.



## Best Solution Provider for Customized Products

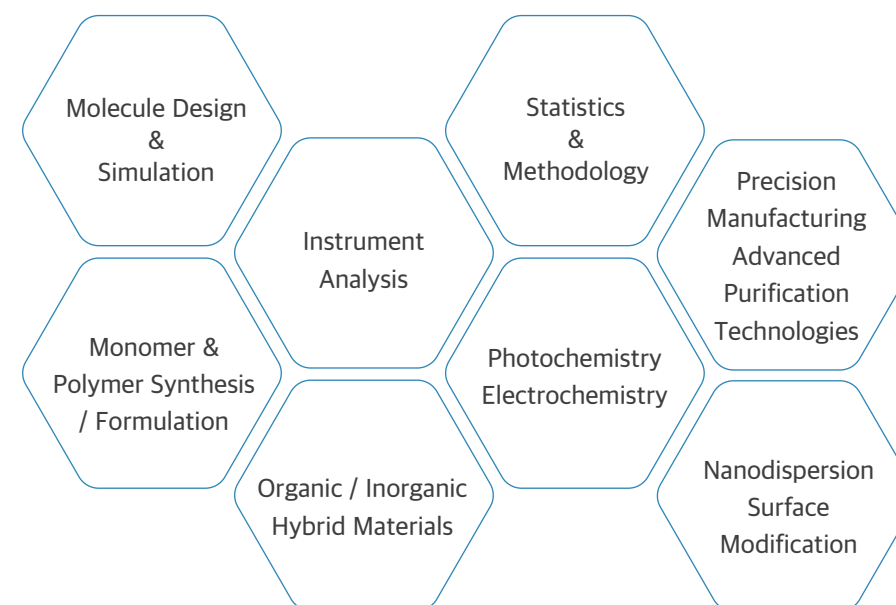
To contribute to our customers' success, we always keep close relationships with clients to design products as desired. Combining our strength in materials expertise and strong manufacturing ability, we aim to be the best solution provider worldwide.



## Research & Development

### Core Technologies and Product Development

All the innovations are the extension of fundamental science. From the basic photochemistry to color simulation, molecular simulation, dispersion science, surface chemistry, organic and inorganic hybrid materials design, monomer & polymer synthesis/formulation, and precision manufacturing and advanced purification technologies, Daxin links all these technologies to provide superior and customer-oriented products in different Semiconductor and Liquid Crystal Display (LCD) fields.



### Consistent Innovation & Intellectual Property Protection

To defend our innovation and ensure the right for production, we are working to improve intellectual property protection and enforcement for our company in markets around the globe. Our patents include all ranges: from specific chemical formula, better solution to current technology, to the improvements of products. Until 2022 the approved patent license number was more than 302, the application number was more than 433. With intellectual property protection, it gives us exclusive right granted for invention and protects our corporate value in the market.

## Semiconductor Materials

### Photosensitive Dielectric/Passivation

#### Dielectric for Redistribution Layer

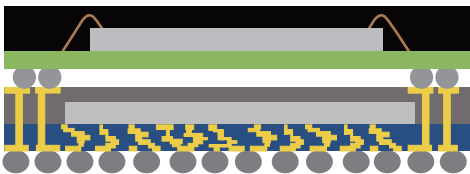
##### Applications

Varnish-type photosensitive dielectrics for the advanced chip packaging (WLP/PLP) are designed, which could be spin or slit-coated into thin film on the substrate and is photosensitive, able to be patterned into multi-layer redistribution layer (RDL). Low curing temperature, excellent Cu adhesion and electric properties are achieved for the varying chip applications.

Multi-chip Fan-Out Package



Fan-Out PoP



##### Features of General Type

- Low temperature curing
- Excellent Cu adhesion
- Low CTE
- High resolution
- Excellent chemical resistance

##### Features of Low Dk/Df Type

- Low temperature curing
- Low Dk/Df
- High resolution
- Excellent chemical resistance

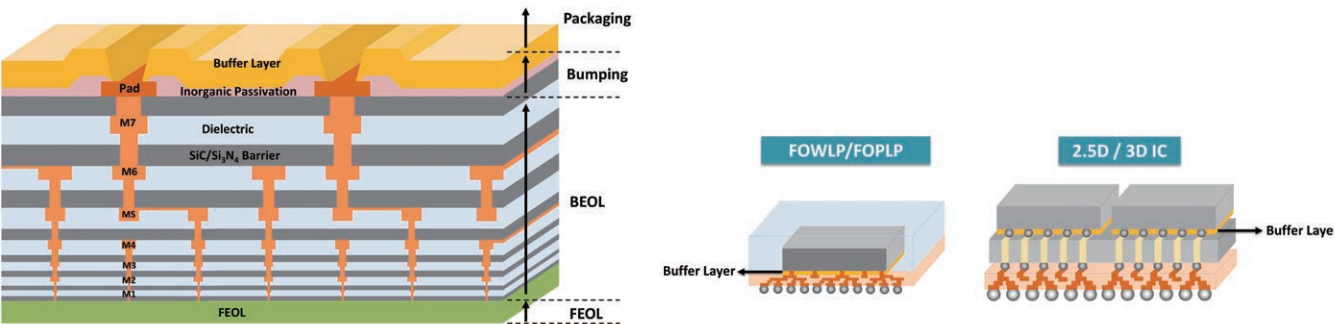
##### Specifications

| Product Name                                                        |                    | RDLT series                                     |            |                                 | RPH series             |
|---------------------------------------------------------------------|--------------------|-------------------------------------------------|------------|---------------------------------|------------------------|
| Features                                                            |                    | Negative-type<br>Low curing temperature<br>PSPi |            | Negative-type<br>Low Df<br>PSPi | Positive-type<br>PSPBO |
| Non-Volatile Matter Content                                         | wt%                | ~40                                             | ~40        | ~40                             | ~25                    |
| Curing Temperature                                                  | °C                 | 230                                             | 180        | 230                             | 250                    |
| UV dosage (i/g/h line)                                              | mJ/cm <sup>2</sup> | 230-300                                         | 230-300    | 200-250                         | 150                    |
| Young's Modulus                                                     | GPa                | 2.13                                            | 2.04       | 2.03                            | 1.9                    |
| Elongation (RT)                                                     | %                  | 50                                              | 40         | 60                              | 12                     |
| T <sub>g</sub>                                                      | °C                 | 230                                             | 200        | 208                             | 269                    |
| CTE(50-100°C)                                                       | ppm/K              | 48.5                                            | 48.1       | 60.4                            | 40.1                   |
| Dk/Df (1GHz)                                                        | -                  | 3.45/0.024                                      | 3.35/0.022 | 3.06/0.0072                     | 3.01/0.020             |
| Reliability<br>* HTS 175°C 168hr<br>* HAST 96hr<br>* TST 200 cycles | -                  | 5B                                              | 5B         | 5B                              | 5B                     |

#### Buffer Layer

##### Applications

Daxin's photosensitive dielectrics, which possess excellent mechanical properties and thermal stability, can be used as buffer layers for the front-end wafer process. Buffer layers can protect low K dielectric layer from stress induced by package processes and increase the reliability of ICs. Also, its high resolution can meet the requirements of low dimension connections and simplify the manufacturing, which can increase the yields and performances of products.



##### Features

- High resolution
- Excellent mechanical properties
- Excellent thermal stability
- Excellent Cu adhesion
- Low CTE

##### Specifications

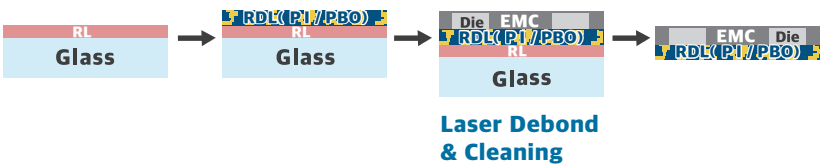
| Product Name                |       | HMPI series |
|-----------------------------|-------|-------------|
| Viscosity                   | cP    | 1000-3500   |
| Non-Volatile Matter Content | %     | 15-40       |
| Young's Modulus             | GPa   | 4.0-5.0     |
| Tensile strength (at break) | MPa   | 150-200     |
| Elongation (at break)       | %     | 20-40       |
| CTE(50-175°C)               | ppm/K | 20-35       |
| T <sub>g</sub>              | °C    | 280-310     |
| Td (5% weight loss)         | °C    | 300-320     |
| Shrinkage                   | %     | 30-50       |
| Aspect ratio                | -     | 0.95-1.5    |

Laser Release Layer

Multi-functional Release Layer

Applications

Temporary bonding of wafer to glass carrier has emerged as a viable method for various electronic device processing. Laser debonding enables the use of laser release layer (RL) that can withstand high temperatures above 300°C. The processed devices are finally debonded and separated from the carriers easily.



Features

- Excellent thermal resistance and stability over 300° C
- Easily stripped by laser
- Applicable under various laser wavelength (308/355/532/1064nm) with high absorption
- Optical alignment (Tunable IR absorption or transmittance)

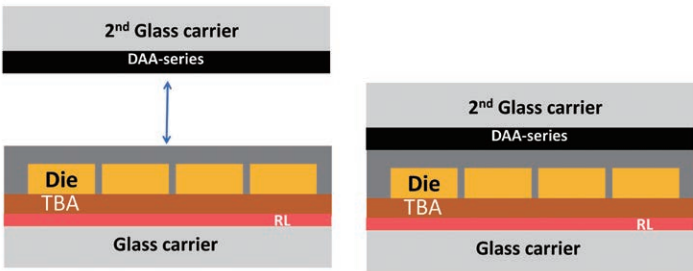
Specifications

| Product Name          |                                         |          | LRA-2 series                                      | Remarks    |
|-----------------------|-----------------------------------------|----------|---------------------------------------------------|------------|
| Field of Applications |                                         |          | Semiconductor                                     |            |
| Features              |                                         |          | High laser absorption efficiency<br>IR absorption |            |
| Varnish               | Non-Volatile Matter Content             | wt%      | 10                                                | Customized |
|                       | Viscosity                               | cp       | 100~200                                           | Customized |
| Process Conditions    | Coating Method                          | -        | Slit or Spin                                      |            |
|                       | Pre-bake                                | °C ; min | 90 ; 10                                           |            |
|                       | Post-bake                               | °C ; min | 250 ; 30                                          |            |
| Thermal Properties    | Td (1%Loss)                             | °C       | ~300                                              | TGA        |
| Optical Properties    | Transmittance                           | %        | <2                                                | 1μm        |
|                       | b*                                      | -        | >2                                                |            |
| Chemical Resistance   | Stripper<br>Aqua Regia<br>Metal Etchant | -        | NO damage                                         |            |

Release Layer For Transfer Bonding

Applications

It is used in temporary bonding & debonding process for wafer/panel level packaging (WLP/PLP). It offers stable adhesion through subsequently physical or chemical processes. It can be debonded by laser easily.



Specifications

| Product Name            |                     |                    | DAA-series                   | Remarks                         |
|-------------------------|---------------------|--------------------|------------------------------|---------------------------------|
| Film Thickness          |                     | μm                 | 5-35                         |                                 |
| Process Conditions      | Pre-bake            | °C ; min           | 50 ; 5<br>90 ; 5<br>150 ; 30 |                                 |
|                         | Bonding Temperature | °C                 | 150~180                      |                                 |
|                         | Bonding Pressure    | kg/cm <sup>2</sup> | 5                            |                                 |
|                         | Bonding Time        | min                | 5                            |                                 |
|                         | Post-bake           | °C ; min           | 230 ; 30                     |                                 |
| Adhesion                |                     | N/mm <sup>2</sup>  | 2                            | Pull test @glass                |
| Thermal Properties      | CTE                 | ppm/K              | 7~8                          | 40~70°C                         |
|                         | Td (5% weight loss) | °C                 | 290                          | By TGA                          |
| Chemical Resistance     | Cross-Cut Test      | -                  | 5B                           | @Glass<br>Stripper, 80°C, 10min |
| Laser Debond Wavelength |                     | nm                 | 355~1064                     |                                 |
| Cleaning Method         |                     |                    | Plasma                       |                                 |

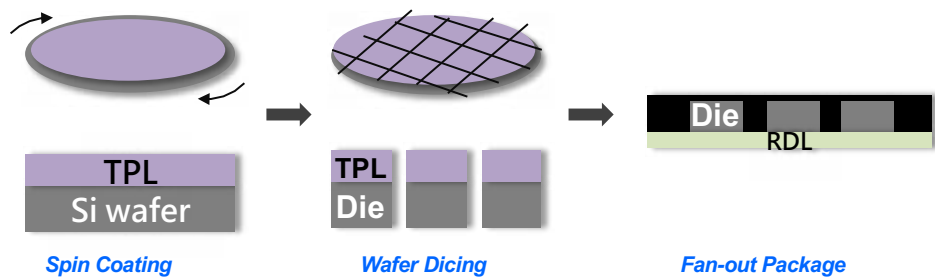


Protection Materials

Temporary Protection Layer

Applications

Temporary Protection Layer is applicable in die singulation process, to protect device surface by spin-coating on the wafer, capable of avoiding die chipping or defects during wafer dicing and grinding. Complete removal of Temporary Protection Layer is achieved by wet cleaning after process.



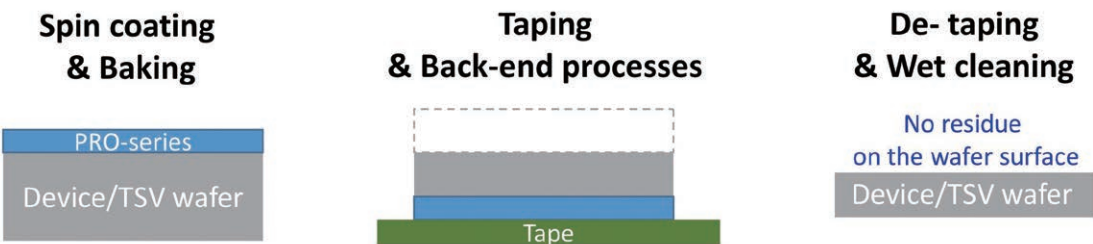
Specifications

| Product Name          |                             |          | TPL-series         |
|-----------------------|-----------------------------|----------|--------------------|
| Field of Applications |                             |          | Advanced Packaging |
| Varnish               | Viscosity                   | cP       | 1000-5000          |
|                       | Non-Volatile Matter Content | wt%      | 10-40              |
| Process Conditions    | Coating Method              | -        | Spin/Slit          |
|                       | Pre-bake                    | °C ; min | 90 ; 10            |
|                       | Post-bake                   | °C ; min | 230 ; 30           |
| Thermal Properties    | T <sub>g</sub>              | °C       | 250                |
| Mechanical Properties | Modulus                     | GPa      | 3                  |
|                       | CTE                         | ppm/K    | 65                 |

Taping protection layer

Applications

It is used in transfer bonding & grinding processes for wafer back-end processes. This material can protect device surfaces and prevent residue of temporary adhesive which may caused electrical problems. This protection layer can be removed by wet cleaning easily.



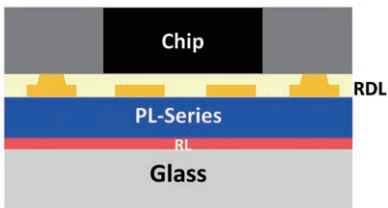
Specifications

| Product Name                |          | PRO-series         | Remarks             |
|-----------------------------|----------|--------------------|---------------------|
| Field of Applications       |          | Advanced packaging |                     |
| Viscosity                   | cP       | 2-50               |                     |
| Non-Volatile Matter Content | wt%      | 2-5                |                     |
| Baking condition            | °C ; min | 120-140 ; 5        |                     |
| Water Resistance            |          | No film loss       | 10min soaking @25°C |
| Cleaning Method             |          | Wet cleaning       | 2.38% TMAH @25°C    |
| Cleaning Time               | sec      | <10                | Thickness=50-100 μm |

Passivation Layer

Applications

Passivation layer is used as an effective strategy to protect the active semiconductor surface from the impact by the surrounding environment. Moreover, the feasibility of laser patterning can be retained.



Specifications

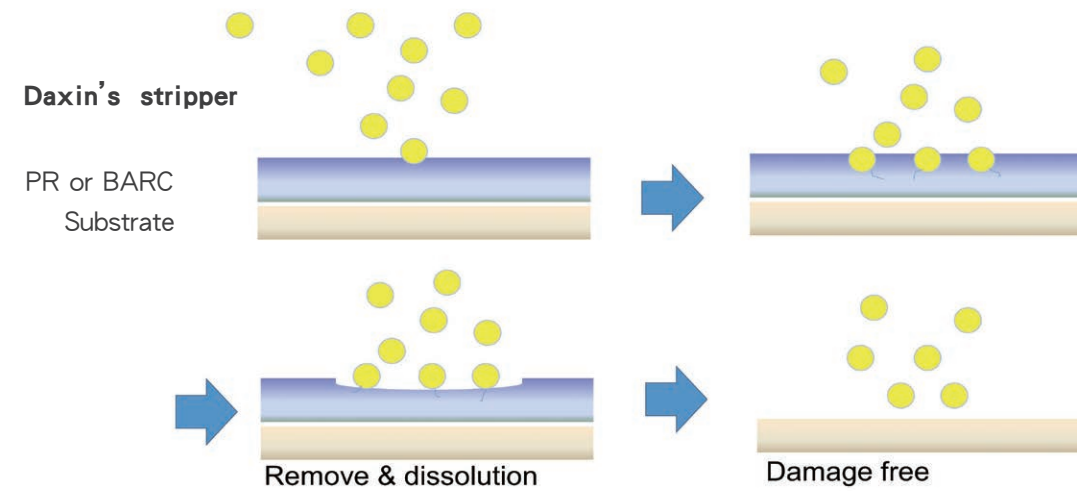
| Product Name                |       | PL series         |
|-----------------------------|-------|-------------------|
| Appearance                  | -     | Transparent/Black |
| Non-Volatile Matter Content | wt%   | 10-20             |
| Curing Temperature          | °C    | 230               |
| Young's Modulus             | GPa   | 2~4               |
| Elongation (RT )            | %     | 50-60             |
| T <sub>g</sub>              | °C    | 230-250           |
| Td 5% Weight Loss           | °C    | >400              |
| CTE (50~100°C )             | ppm/K | 30-50             |

High-Purity Specialty Chemicals for Wet Clean Process

Strippers Removers

Applications

Daxin's formulated strippers and removers are designed for effective removal of photoresist (PR) or bottom anti-reflection coating (BARC) with high protection and compatibility to metal or silicon congaing substrate, which are applicable in advanced IC process.



Features

- Effective removability of thick resist
- Effective removability of PERs/PARs
- Low metal etching rate
- Non-NMP/DMSO solvent system
- High flash point
- High purity (metal ions<1ppb)

Removers

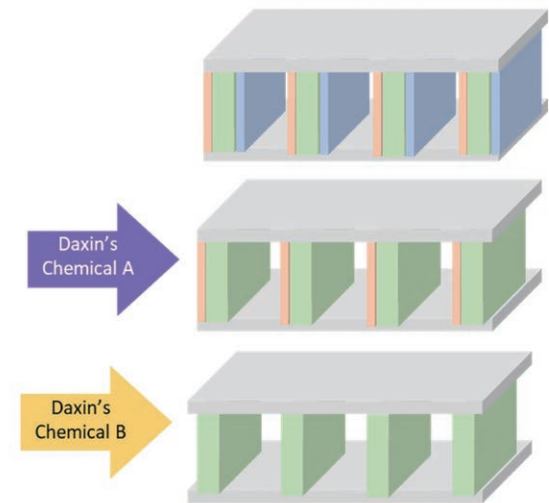
Applications

With the development of new-generation process technologies, the 3D structures in semiconductor processes are constantly evolving, and the materials in integrated circuits are becoming more complex.

To address the inter-mixing between different materials and the development of selective deposition structures, Daxin provides customized removers to meet the needs of microstructure fabrication, which can include the removal of metal-organic materials and the by-products formed during the dry etching process.

Features

- High wettability
- High selectivity
- Customized materials design
- Low inter-mixing effect
- High purity/Low metal ions



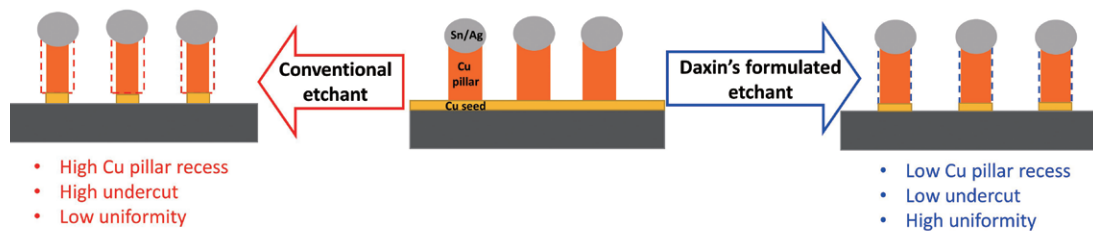
Selective Etchants

Applications

The specifications and purity of wet chemicals are continuously increasing due to the leading technology. Daxin provides a variety of solutions for different etch selectivity between materials.

Daxin's selective etchants can demonstrate high metal loading and can be applied during the reclaim mode process. Without environmentally hazardous substances, not only the process cost but also chemical waste can be reduced.

Furthermore, various advantageous properties such as low undercut and high uniformity can be achieved by crystal orientation-dependent etching so that it can be applied to fine-pitch packages.



High-Purity Specialty Chemicals for Nanolithography

High-Purity Solvent

With advanced purification technologies, Daxin provides high purity solvent which can be used in the semiconductor/display industries and fulfills the needs of low metal ions and low particle content.

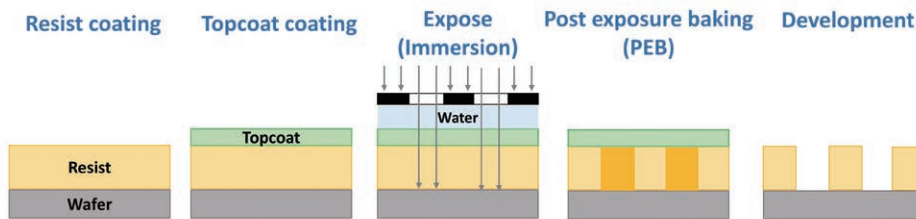
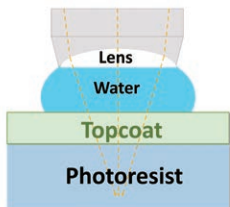
Topcoat

Applications

Daxin provides topcoat materials for immersion lithography, which can prevent photoresist from composition change due to substances dissolving into liquid (ex: water). In addition, topcoat materials can be used for refractive index adjustment. A variety of specialty chemicals for nanolithography process are under development.

Features

- Good water-repellent
- Good dissolution in developer
- No intermixing and dissolution with photoresist



Specifications

| Product Name      |                                  |          | DTC-series | Remarks                      |
|-------------------|----------------------------------|----------|------------|------------------------------|
| Varnish           | Non-Volatile Matter Content      | wt%      | 2.5        | Customized                   |
|                   | Viscosity                        | cP       | 0.8        | Customized                   |
| Process condition | Pre-bake                         | °C ; min | 80 ; 1     |                              |
| Film Properties   | Refractive Index at 193 μm       | -        | 1.53-1.60  | Thickness=500Å<br>Customized |
|                   | Extinction Coefficient at 193 μm | -        | <0.01      |                              |
|                   | Receding Angle                   | degree   | 70-75      |                              |
|                   | Dissolution Rate                 | μm/sec   | 200-400    | 2.38%TMAH                    |



## Display Materials

### LCD Materials

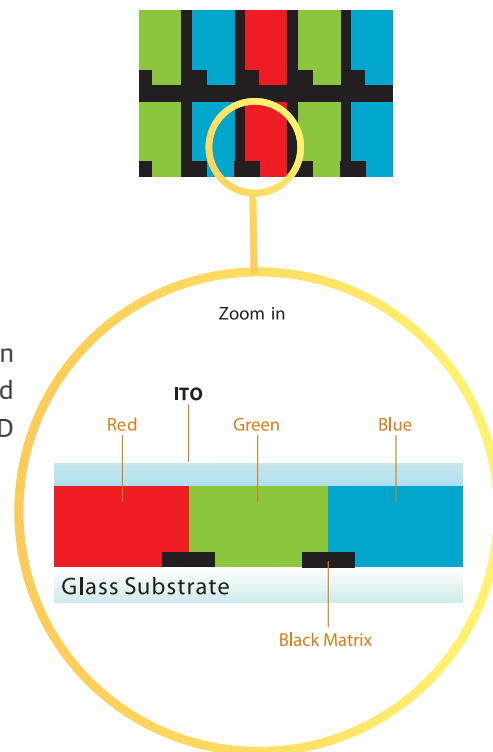
#### Black Matrix Resist

##### Applications

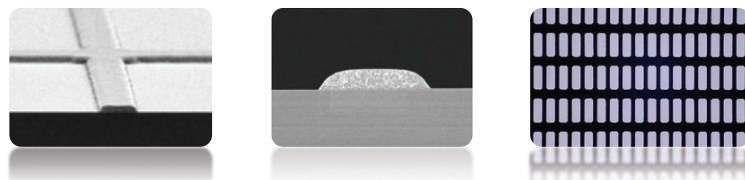
Black matrix is arranged in the form of stripes, grids or mosaics between color patterns of RGB in color filter for LCD panel. This product is designed for high light-shielding properties to increase the contrast ratio of LCD panel.

##### Features

- High optical density
- High coating uniformity, high sensitivity, excellent adhesion, excellent developing performance
- Excellent reliability in heat, light, and chemical resistance with good shelf-life
- New: Black matrix resist for LCD panel with high resolution



##### Specifications



| Product Name                |                  |                                                  | ABK406X              | ABK408X                            | Remarks                                                  |
|-----------------------------|------------------|--------------------------------------------------|----------------------|------------------------------------|----------------------------------------------------------|
| Field of Application        |                  |                                                  | Full High Definition | Ultra High Definition              |                                                          |
| Features                    |                  |                                                  | Standard             | High Resolution<br>High Resistance |                                                          |
| Viscosity                   | cP               |                                                  | 3.0±0.5              | 3.0±0.5                            |                                                          |
| Non-Volatile Matter Content | wt%              |                                                  | 13-15                | 13-15                              |                                                          |
| Line Width                  | μ m              |                                                  | 6-30                 | 4-8                                |                                                          |
| Remaining Film Thickness    | %                |                                                  | 75-85                | 75-85                              | After PB/Before PB (PB: 230°C×20min)                     |
| Process Conditions          | Pre-bake         | °C ; sec                                         | 70-120 ; 90          | 70-120 ; 90                        |                                                          |
|                             | Exposure Energy  | mJ/cm <sup>2</sup>                               | 40-100               | 45-100                             |                                                          |
|                             | Development      |                                                  | KOH/Buffer           | KOH/Buffer                         | At 23°C-25°C                                             |
|                             | Post-bake        | °C ; min                                         | 230 ; 20             | 230 ; 20                           |                                                          |
| Optical Density             |                  | 1/μ m                                            | 4.5-4.0              | 4.0-3.0                            |                                                          |
| Surface Resistivity         |                  | Ω/□                                              | 1×10 <sup>9</sup>    | >1×10 <sup>14</sup>                |                                                          |
| Chemical Resistance         | IPA              | (OD <sub>Before</sub> -OD <sub>After</sub> )/μ m | <0.1                 | <0.1                               | After25°C Dip 5min +120°C ×2min                          |
|                             | NMP              |                                                  |                      |                                    | After25°C Dip 5min + 240°C ×15min                        |
|                             | y-buthyrolactone |                                                  |                      |                                    |                                                          |
| Weight Loss                 | %                |                                                  | <3                   | <3                                 | After PB + 230°C × 60min by TGA                          |
| Pressure Cook Test          |                  |                                                  | 5B                   | 5B                                 | After PB + 230°C ×180min<br>121°C, 2atm, RH100% for 24hr |

#### Photo Spacer

##### Applications

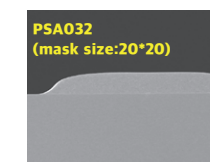
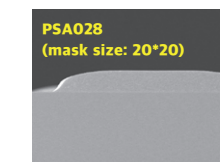
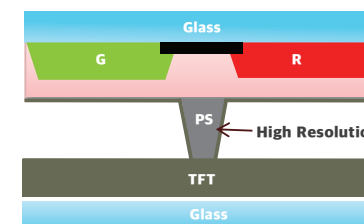
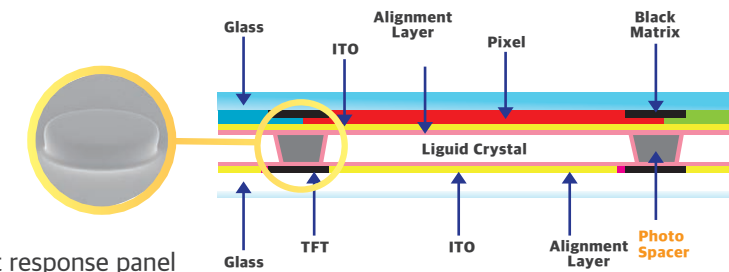
Via adjusting electric field between two glass substrates, the arrangement of liquid crystal materials can be controlled to make LCD exhibit expected pictures. Photo Spacer acts as a key component in TFT LCD which is used to maintain the cell gap's uniformity.

##### Features

- High sensitivity
- Good coatability
- High elastic recovery ratio
- Excellent mechanical properties
- New:

High resolution photo spacer for fast response panel

Applicable for ultra-high LCD cell thick panel



##### Specifications

| Product Name          |                                    |     | Normal PS                                                                                                                                            | Low Cell Gap-HPS                                                                                                                          | Ultra High PS                                                                                                                      |
|-----------------------|------------------------------------|-----|------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------|
| Field of Applications |                                    |     | TN/VA/PSA/COA                                                                                                                                        | AFFS                                                                                                                                      | 3Ddisplay/electro-chromic glass                                                                                                    |
| Features              |                                    |     | <ul style="list-style-type: none"> <li>Widely used in different process conditions</li> <li>Wide LC margin, Excellent pressure resistance</li> </ul> | <ul style="list-style-type: none"> <li>Applicable in fast response high-resolution screens</li> <li>Stable with low volatility</li> </ul> | <ul style="list-style-type: none"> <li>High aspect ratio, thickness can be achieved to 45 μ m</li> <li>High taper angle</li> </ul> |
| Physical Properties   | Viscosity                          | cP  | 4.3±0.3                                                                                                                                              | 3.25±0.3                                                                                                                                  | 5.1±0.3                                                                                                                            |
|                       | Non-Volatile Mater Content         | wt% | 18.7±0.5                                                                                                                                             | 23.2±0.5                                                                                                                                  | 23.3±0.5                                                                                                                           |
|                       | Remanent                           | %   | 88.5±2                                                                                                                                               | 86±2                                                                                                                                      | 90±2                                                                                                                               |
|                       | Resolution                         | μ m | 10*10                                                                                                                                                | 5*5                                                                                                                                       | 20*20                                                                                                                              |
| Optical Properties    | Height diff. between main & sub PS | μ m | 0.3-0.7                                                                                                                                              | 0.3-0.5                                                                                                                                   | -                                                                                                                                  |
|                       | (460nm) Transmittance              | %   | >96                                                                                                                                                  | >96                                                                                                                                       | >96                                                                                                                                |
|                       | (540nm) Transmittance              | %   | >97                                                                                                                                                  | >97                                                                                                                                       | >97                                                                                                                                |
|                       | Sensitivity                        | mJ  | 40-50                                                                                                                                                | 40-50                                                                                                                                     | 70                                                                                                                                 |
| Mechanical Properties | Hardness                           |     | 5H                                                                                                                                                   | 8H                                                                                                                                        | 6H                                                                                                                                 |
|                       | Recovery Ratio                     | %   | >88<br>(40 mN, mask size: 20×20 μ m)                                                                                                                 | >80<br>(40 mN, mask size: 10×10 μ m)                                                                                                      | >90<br>(50 mN, mask size: 28×28 μ m)                                                                                               |
|                       | Adhesion Test                      |     | 5B                                                                                                                                                   | 5B                                                                                                                                        | 5B                                                                                                                                 |
| Electrical Properties | Dielectric Constant                |     | 3.7                                                                                                                                                  | 3.7                                                                                                                                       | 3.7                                                                                                                                |
|                       | Voltage Holding Ratio              | %   | >95                                                                                                                                                  | >95                                                                                                                                       | >95                                                                                                                                |
| Chemical Resistance   | Heat water/KOH/TMAH/IPA/GBL        |     | Pass                                                                                                                                                 | Pass                                                                                                                                      | Pass                                                                                                                               |

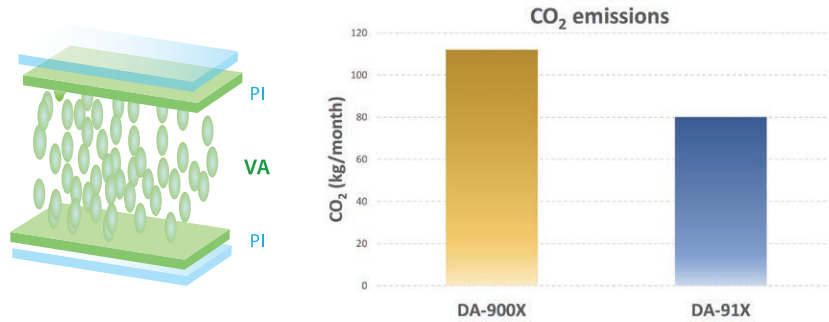
PI Alignment Layer (PSA-mode)

Applications

The main function of Polyimide alignment film material is to control the orientation of liquid crystal molecules and provide a pretilt angle for the liquid crystal. The PSA-mode provided by Daxin Materials is mainly used in the alignment film material for TVs, enabling the liquid crystal components to have excellent performance and wide processability conditions.

Features

- No image sticking
- High VHR and excellent reliability
- Stable pre-tilt angle
- Drop mura free
- Excellent adhesion
- Excellent coating properties



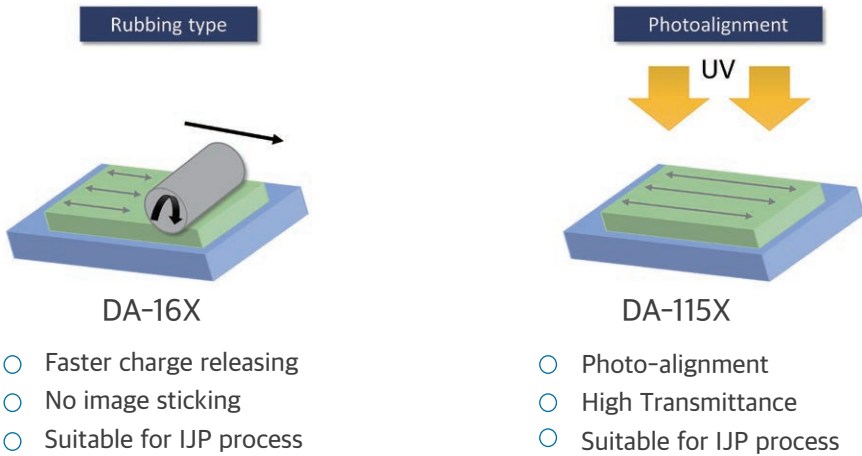
Specifications

| Product Name                |          | DA-90X                                    | DA-63X                               | DA-91X                             |
|-----------------------------|----------|-------------------------------------------|--------------------------------------|------------------------------------|
| Field of Application        |          | Normal type                               |                                      | Pioneer ESG                        |
| Features                    |          | 1. Drop Mura Free<br>2. No Image Sticking | Suitable for PFA Type PSA-LCD        | Low hard bake temperature          |
| Viscosity                   | cP       | 6-25                                      | 6-25                                 | 14-22                              |
| Non-Volatile Matter Content | wt%      | 3.0-7.0                                   | 3.0-7.0                              | 6.0-7.0                            |
| Water Content               | ppm      | <2000                                     | <2000                                | <2000                              |
| Ionic Impurities            | ppb      | <500 (Na, K, Cu, Fe)                      | <500 (Na, K, Cu, Fe)                 | <500 (Na, K, Cu, Fe)               |
| Pre-Bake                    | °C ; min | 70-90 ; 2                                 | 70-90 ; 2                            | 70-90 ; 2                          |
| Post-Bake                   | °C ; min | 210-230 ; 15-60                           | 21-230 ; 15-60                       | 180 ; 30                           |
| Pre-tilt Angle              | °        | 88-90                                     | 88-90                                | 88-90                              |
| Voltage Holding Ratio, VHR  | %        | >90                                       | >90 (Normal)<br>>80 (After PCT 12hr) | > 90                               |
| Ion Density                 | pC       | <5000                                     | <5000                                | <5000                              |
| Residue DC                  | mV       | <100                                      | <100                                 | <100                               |
| Volume Resistivity          | Ω · cm   | 10 <sup>11</sup> ~10 <sup>13</sup>        | 10 <sup>11</sup> ~10 <sup>13</sup>   | 10 <sup>11</sup> ~10 <sup>12</sup> |

PI Alignment Layer(FFS-mode)

Applications

The main function of Polyimide alignment film material is to control the orientation of liquid crystal molecules and provide a pretilt angle for the liquid crystal. The FFS-mode provided by Daxin Materials is mainly used in the alignment film material for TVs, enabling the liquid crystal components to have excellent performance and wide processability conditions.



Specifications

| Product Name                |                    | DA-110X                                             | DA-160X                                                                  | DA-115X                                                                            |
|-----------------------------|--------------------|-----------------------------------------------------|--------------------------------------------------------------------------|------------------------------------------------------------------------------------|
| Field of Application        |                    | Normal type                                         | High-wear resistant type                                                 | Photoalignment type                                                                |
| Features                    |                    | 1. Good Rubbing Resistance<br>2. High transmittance | 1. Faster charge releasing<br>2. No Image Sticking<br>3. Inkjet Printing | 1. High transmittance<br>2. Excellent Printing Performance and Electric Properties |
| Viscosity                   | cP                 | 40-45                                               | 11-13                                                                    | 6-9                                                                                |
| Non-Volatile Matter Content | wt%                | 6.5-7.5                                             | 2.5-3.5                                                                  | 2-4                                                                                |
| Water Content               | ppm                | <2000                                               | <2000                                                                    | <2000                                                                              |
| Ionic Impurities            | ppb                | <200 (Na, K, Cu, Fe)                                | <200 (Na, K, Cu, Fe)                                                     | <200 (Na, K, Cu, Fe)                                                               |
| Pre-Bake                    | °C ; S             | 80                                                  | 100 ; 130                                                                | 80                                                                                 |
| Post-Bake                   | °C ; min           | 230 ; 30                                            | 230 ; 20                                                                 | 230 ; 30                                                                           |
| Exposure dose               | mJ/cm <sup>2</sup> | -                                                   | -                                                                        | 200-500                                                                            |
| Pre-tilt Angle              | °                  | 1.5-3.0                                             | 1.5-2.5                                                                  | <1.0                                                                               |
| Voltage Holding Ratio, VHR  | %                  | >90                                                 | >90                                                                      | >90                                                                                |
| Ion Density                 | pC                 | <10000                                              | <10000                                                                   | <10000                                                                             |
| Flicker-RDC                 | -                  | Faster charge releasing<br>Free image sticking      | Faster charge releasing<br>Free image sticking                           | Faster charge releasing<br>Free image sticking                                     |
| Volume Resistivity          | Ω · cm             | 10 <sup>13</sup> ~10 <sup>14</sup>                  | 10 <sup>12</sup> ~10 <sup>13</sup>                                       | 10 <sup>12</sup> ~10 <sup>13</sup>                                                 |

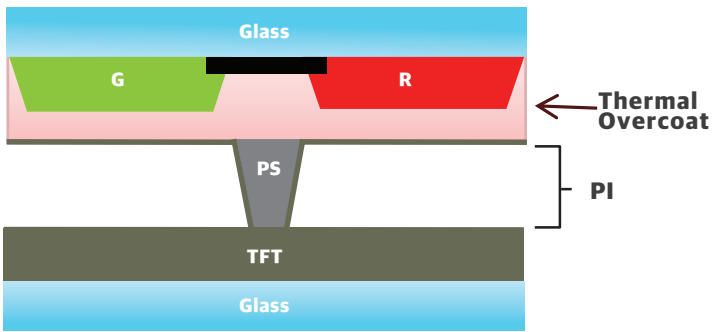
Thermal Overcoat

Applications

Thermal overcoat is applied to IPS-like panel and acts a transparent planarization layer on Color resists (RGB) and Black matrix (BM), protecting color filter and providing flat surface to ensure subsequent process uniformity.

Features

- High transparency
- Excellent planarization ability
- Good heat and chemical resistivity
- Low UV transmittance, which protect RGB from UV damage
- High crosslink ratio



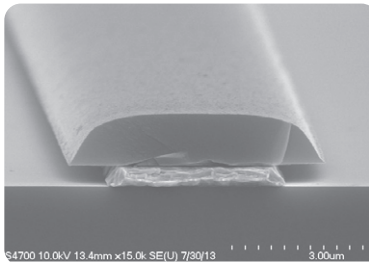
Specifications

| Product Name              |                           |     | DTOCVS                                   | DTOCV6                           | Remarks                  |
|---------------------------|---------------------------|-----|------------------------------------------|----------------------------------|--------------------------|
| Field of Applications     |                           |     | IPS model with Photo Alignment PI        | IPS model with Rubbing type PI   |                          |
| Features                  |                           |     | high hardness good orechemical resistivi | excellent pplanarization ability |                          |
| Basic Properties          | Flatness (OC THK=1.6 μ m) | μ m | 0.37                                     | 0.25                             | Max-Min (Δ Hx)           |
|                           | Remanent                  | μ m | 0.17                                     | 0.10                             | Δ RGB                    |
|                           | Adhesion (on glass)       | %   | 97.6%                                    | 92.3%                            | 230°C/30min              |
|                           |                           | -   | 4-5B                                     | 5B                               | PCT121°C/2atm/12hr       |
| Machanical Properties     | Pencil Hardness           | -   | 6H                                       | 5H                               | @765g                    |
| Optical Properties        | Transmittance             | %   | 99.8                                     | 99.7                             | @400 μ m                 |
|                           |                           | %   | 46.9                                     | 71.1                             | @313 μ m                 |
|                           |                           | %   | 9.6                                      | 33.8                             | @254 μ m                 |
| Heat& Chemical Resistance | TGA weight loss           | %   | 0.25                                     | 0.17                             | Water Absorption         |
|                           |                           | %   | 0.20                                     | 0.25                             | Out-gassing              |
|                           | NMP elution test          | -   | 0.000                                    | 0.002                            | OC on Red Resist@520 μ m |

Cu/Mo Etchant

Features

- Hydrogen peroxide type is environmental friendly
- Good stability for very high copper loading (> 10k ppm)
- Good etching uniformity
- Good taper profile after etching.



Specifications

| Test Items                                  | Unit  | DE-series   | Remarks |
|---------------------------------------------|-------|-------------|---------|
| Max.Cu Loading                              | ppm   | > 10k       |         |
| Etching Rate                                | Å/min | 4,000-6,000 | 35°C    |
| pH value                                    |       | 3.7-4.4     |         |
| H <sub>2</sub> O <sub>2</sub> Concentration | %     | 6-8.5       |         |
| Taper                                       | °     | 30-70       |         |

Cu Stripper

Features

- Non-Corrosive to Cu, Mo, Al, ITO and IGZO
- Water compatible, favorable for post-clean process
- Regenerable and environmental friendly
- Low toxicity, no reproductive toxicity



Specifications

| Test Items      | Unit              | GD-series                 | Remarks |
|-----------------|-------------------|---------------------------|---------|
| Appearance      |                   | Colorless to light yellow |         |
| Density         | g/cm <sup>3</sup> | 1.062-1.082               |         |
| pH value        |                   | 11                        | 15% aq. |
| Solubility      |                   | Soluble in water          |         |
| Operating Temp. | °C                | 40-50                     |         |

Touch Panel Materials

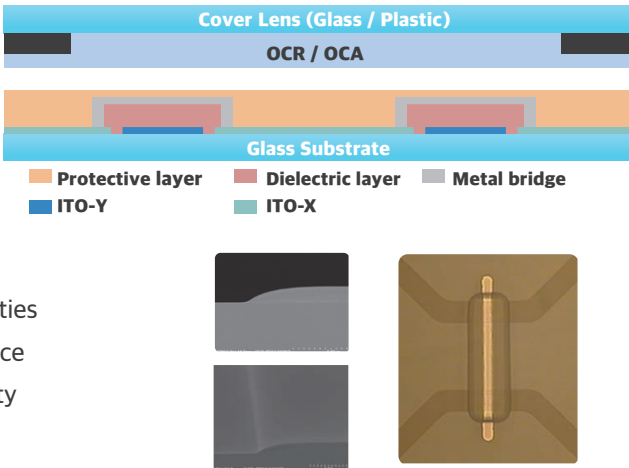
Photo Overcoat

Applications

Photo overcoat is applied in touch sensor a dielectric layer and a insulating layer. Photo overcoat contains good properties of insulation, adhesion, chemical resistance and hardness.

Features

- Optical properties: high transparency and good color hue
- Mechanical properties: good adhesion to bare glass, ITO and metal substrates; good hardness
- Electrical properties: excellent insulating properties
- Chemical properties: excellent chemical resistance
- Process window: easy to coat and high sensitivity



Specifications

| Product Name                |                   |          | POCA               | Remarks            |
|-----------------------------|-------------------|----------|--------------------|--------------------|
| Field of Application        |                   |          | General POC        |                    |
|                             |                   |          | Slit & Spin Type   |                    |
| Features                    |                   |          | Spin or Spray Type |                    |
| Viscosity                   | cP                |          | 4-7±1              | At25°C, 60rpm      |
| Non-Volatile Matter Content |                   |          | wt%                | 18-25±1            |
| Process Conditions          | Pre-bake          | °C ; sec | 90-110 ; 90        |                    |
|                             | Exposure Energy   | mJ/cm²   | 50-100             |                    |
|                             | Mask              |          | Soda-lime & Quartz |                    |
|                             | Development       |          | KOH                |                    |
|                             | Post-bake         | °C ; min | 220-240 ; 30       |                    |
| Transmittance at 400nm      |                   |          | %                  | >95                |
| Refractive index at 633nm   |                   |          |                    | 1.51-1.52          |
| Surface Resistivity         |                   |          | Ω/ □               | 1×10 <sup>14</sup> |
| Dielectric constant         |                   |          |                    | 4.3                |
| Hardness                    |                   |          |                    | 3H                 |
| Shrinkage                   |                   |          | %                  | 88±2.0             |
| Remaining Film Thickness    |                   |          | %                  | 85±3.0 (100mJ/cm2) |
| Chemical Resistance         |                   |          |                    | 5B                 |
| HT/HH(65°C/90%, 240hrs)     | Adhesion on Glass |          |                    | ASTM-D3359         |
|                             | Adhesion on ITO   |          | 5B                 |                    |
|                             | Adhesion on Metal |          | 4B                 |                    |

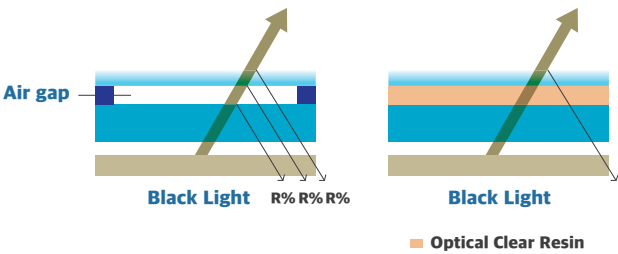
Optical Clear Resin

Applications

OCR(Optical clear resin) is an optical grade adhesive applied on laminated cover lens, touch panels and LCD modules. OCR can improve visibility and contrast ratio by reducing the reflection light between the interfaces in cover lens, touch panels or LCMs.

Features

- High transmittance
- Easy to rework
- Excellent adhesion on cover lens, touch panels and LCMs
- Non-yellowing, low dosage
- Fast cure, low dosage



Specifications

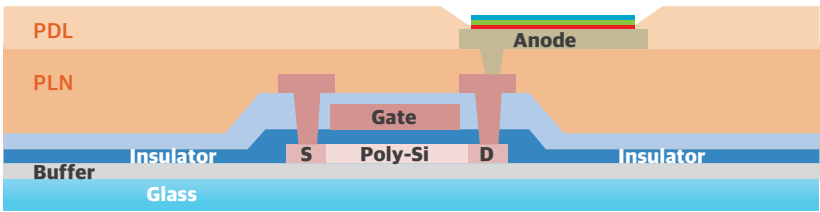
| Product Name                                  |        | OCRP198                                                                       | Remarks                                          |
|-----------------------------------------------|--------|-------------------------------------------------------------------------------|--------------------------------------------------|
| Field of Application                          |        | DGS/LCM&GFF/<br>LCM&On-cell                                                   |                                                  |
| Features                                      |        | • Low Modulus for Mura Free<br>• Easy to rework<br>• High Dielectric Constant |                                                  |
| Viscosity                                     | cP     | 2,900                                                                         | Brook Field Viscometer<br>at 25.0±1.0°C , CPE 51 |
| Non-Volatile Matter Content                   |        | wt%                                                                           | 100                                              |
| Exposure Energy                               | mJ/cm² | 2,000-5,000                                                                   | Depend on UV lamp                                |
| Operating Environment<br>(Yellow/White Light) |        | Yellow                                                                        |                                                  |
| Transmittance at 400nm                        | %      | >95                                                                           | THK0.3mm G/G                                     |
| Yellow Index                                  |        | 0.55                                                                          | THK0.3mm G/G                                     |
| Haze                                          | %      | 0.26                                                                          | THK0.3mm G/G                                     |
| Tensile Adhesion                              | kPa    | 210                                                                           | THK0.3mm G/G<br>*THK0.15mm G/G                   |
| Elongation                                    | %      | 2,500                                                                         |                                                  |
| Elastic Modulus                               | kPa    | 2.3                                                                           |                                                  |
| Dielectric Constant                           |        | 5.2                                                                           | 1MHz                                             |

Flexible EPD/OLED Materials

Photosensitive Dielectric/Passivation

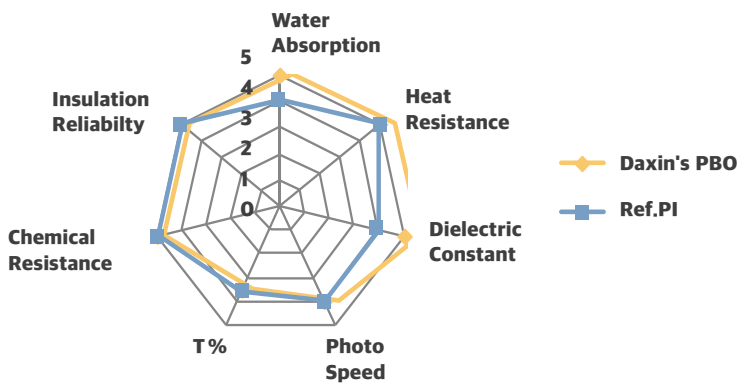
Applications

PBO dielectric layers can be used as the pixel defining layer (PDL) over the pixel electrode or the planarization layer (PLN) covering the TFTs in an organic light emitting diode display (OLED) and Electronic Paper Display (EPD).



Features

- Low water absorption
- Low dielectric constant
- Precision planarization capabilities
- Excellent mechanical and thermal properties
- High chemical resistance
- New : UV-resistance



Specifications

| Product Name         |    | PDLN-200 Series                         |                                        |                                        | Remarks                                                            |
|----------------------|----|-----------------------------------------|----------------------------------------|----------------------------------------|--------------------------------------------------------------------|
| Pattern Availability |    | PLN                                     | PDL                                    | PS                                     |                                                                    |
| Features             |    | THK 2.0 μm<br>Via5-6 μm<br>Taper50°-60° | THK 1.5 μm<br>Via10-15 μm<br>Taper<30° | THK 1.0 μm<br>Dot10-15 μm<br>Taper<30° |                                                                    |
| Water Absorption     | %  | (1)0.11<br>(2)0.39                      |                                        |                                        | TGA(RA85/85,24Hr)<br>(1)30°C, 30min<br>(2)120°C, 10min<br>10°C/min |
| Td(1%)               | °C | 293                                     |                                        |                                        |                                                                    |
| Weight Loss          | %  | 0.57                                    |                                        |                                        | After250°C/1hr                                                     |
| Chemical Resistance  | -  | 5B                                      |                                        |                                        | TMAH, Stripper,<br>Ag etchant,<br>Oxalic acid                      |
| Dielectric Constant  | -  | 3.43<br>3.21                            |                                        |                                        | @1kHz<br>@1MHz                                                     |
| Recovery Ratio       | %  | 55.4                                    |                                        |                                        | Bump size:<br>10 μm× 10 μm<br>THK: 1 μm                            |
| Transmittance        | %  | 94.5                                    |                                        |                                        | THK1.5 μm at<br>550 μm                                             |



MircoLED Materials

Bank Materials

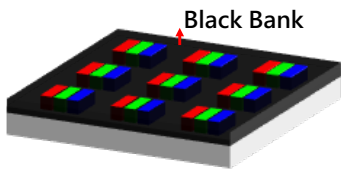
Applications

Black bank / white bank materials are used as the separation of LED chips for Micro LED displays. Black bank with high optical density can increase the contrast. White bank with high reflectance can increase the brightness. Bank materials are available based on the product designs.

Black Bank

Features

- High optical density
- High electrical resistance
- Excellent weather resistance



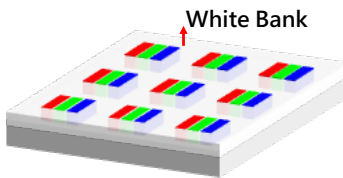
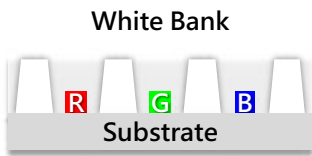
Specifications

| Test Items          | Unit | DBB-series         | Remarks            |
|---------------------|------|--------------------|--------------------|
| Viscosity           | cP   | 10-15              |                    |
| Optical Density     | --   | 2.0                | @Thickness= 10 μm  |
| Surface Resistivity | Ω/ □ | > 10 <sup>15</sup> |                    |
| HT/HH Test          | --   | 5B                 | 60°C , 90%RH, 240h |

White Bank

Features

- High reflectance
- High electrical resistance
- Excellent weather resistance



Specifications

| Test Items          | Unit | DBB-series         | Remarks            |
|---------------------|------|--------------------|--------------------|
| Viscosity           | cP   | 10-15              |                    |
| Reflectance@550nm   | --   | >70                | @Thickness= 10 μm  |
| Surface Resistivity | Ω/ □ | > 10 <sup>15</sup> |                    |
| HT/HH Test          | --   | 5B                 | 60°C , 90%RH, 240h |



## Key Raw Materials

### Functional Monomer

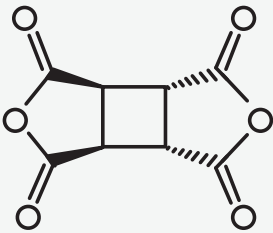
#### CBDA

Cyclobutane-1,2,3,4-tetracarboxylic dianhydride (CBDA) is an alicyclic dianhydride.

Based on our unique photochemical reaction, we can synthesize the core structure of cyclobutane and the configuration of CBDA can be determined to be cis-trans-cis.

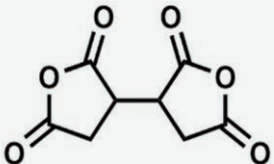
CBDA is widely used as a raw material for polyimide resins or polyamic acid resins because of its high reactivity during polymerization. In the application of display materials, such as alignment films for liquid-crystal-display devices, CBDA provides excellent electrical properties such as high VHR (Voltage Holding Rate) and low RDC (residual DC Voltage Measurement).

Furthermore, polymers made of CBDA offer good transparency and excellence flexibility, and therefore it is a good candidate for flexible substrate applications.

| Properties              |                                                | Structure                                                                                                     |
|-------------------------|------------------------------------------------|---------------------------------------------------------------------------------------------------------------|
| Formula                 | C <sub>8</sub> H <sub>4</sub> O <sub>6</sub>   |  <p>cis-trans-cis form</p> |
| CAS Number              | 4415-87-6                                      |                                                                                                               |
| Molecular Weight        | 196.11                                         |                                                                                                               |
| Appearance              | White Powder                                   |                                                                                                               |
| Melting Point           | >300°C                                         |                                                                                                               |
| Ion Content(Na,K,Cu,Fe) | <500 ppb                                       |                                                                                                               |
| Solubility              | Soluble in NMP, DMAc<br>Slight soluble in Ac2O |                                                                                                               |

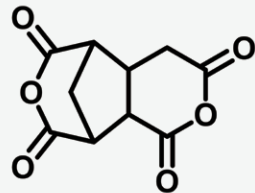
#### BDA

Meso-Butane-1,2,3,4-tetracarboxylic dianhydride (BDA) has good dielectric properties and flexibility which makes it widely used in polyimide resins or polyamic acid resins.

| Properties                  |                                              | Structure                                                                            |
|-----------------------------|----------------------------------------------|--------------------------------------------------------------------------------------|
| Formula                     | C <sub>8</sub> H <sub>6</sub> O <sub>6</sub> |  |
| CAS Number                  | 4534-73-0                                    |                                                                                      |
| Molecular Weight            | 198.13                                       |                                                                                      |
| Appearance                  | white powder                                 |                                                                                      |
| Melting Point               | >240°C                                       |                                                                                      |
| Ion Content (Na, K, Cu, Fe) | <500ppb                                      |                                                                                      |
| Solubility                  | Soluble in NMP, DMAc                         |                                                                                      |

#### TCA

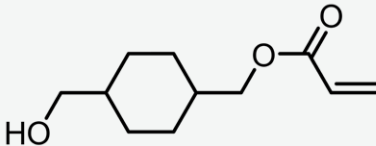
3-(Carboxymethyl)-1,2,4-cyclopentanetricarboxylic Acid 1,4:2,3-dianhydride (TCA) is an alicyclic dianhydride, which is widely used as a raw material for polyimide resins or polyamic acid resins in the application of alignment films for liquid-crystal-display devices due to good solubility and thermal stability. Based on our own developed synthetic process, TCA can be obtained in high purity with low ion content.

| Properties                  |                                               | Structure                                                                           |
|-----------------------------|-----------------------------------------------|-------------------------------------------------------------------------------------|
| Formula                     | C <sub>10</sub> H <sub>8</sub> O <sub>6</sub> |  |
| CAS Number                  | 6053-46-9                                     |                                                                                     |
| Molecular Weight            | 224.17                                        |                                                                                     |
| Appearance                  | white powder                                  |                                                                                     |
| Melting Point               | >197°C                                        |                                                                                     |
| Ion Content (Na, K, Cu, Fe) | <500ppb                                       |                                                                                     |
| Solubility                  | Soluble in NMP, DMAc                          |                                                                                     |

#### Monoacrylate

##### CHDMMA

1,4-Cyclohexanedimethanol monoacrylate(CHDMMA) is manufactured with high purity by Daxin unique synthesis method and widely applied to coating, photoresist and adhesives.

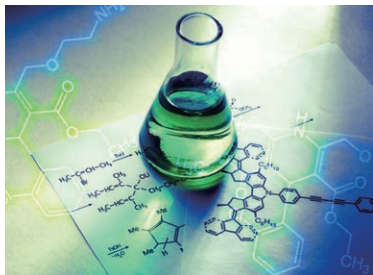
| Properties       |                                                | Structure                                                                             |
|------------------|------------------------------------------------|---------------------------------------------------------------------------------------|
| Formula          | C <sub>11</sub> H <sub>18</sub> O <sub>3</sub> |  |
| CAS Number       | 23117-36-4                                     |                                                                                       |
| Molecular Weight | 198.26                                         |                                                                                       |
| Appearance       | Transparent liquid                             |                                                                                       |
| Viscosity(25°C)  | 90-105cPs                                      |                                                                                       |
| Purity           | >98%                                           |                                                                                       |



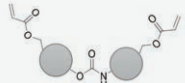
Specialty Polymer

Modified Acrylate

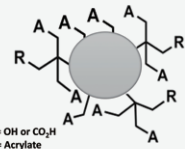
Daxin is committed to providing a wide range of modified acrylate oligomers and polymers with high performance, such as high reactivity, high adhesion and ability of development, to satisfy customer’s requirements of high-end products. Daxin’s modified acrylates have been used in the optical adhesives, photoresists for display, UV coatings, and other specialty applications.



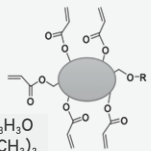
Polyurethane Acrylate

| Product name | Structure                                                                         | Functionality | Viscosity (cP @ 25℃ ) | D <sub>k</sub> (@1MHz) | Characteristics                       | Applications |
|--------------|-----------------------------------------------------------------------------------|---------------|-----------------------|------------------------|---------------------------------------|--------------|
| DAU001       |  | 2             | 54,000-68,000         | 5.2                    | Flexibility, High elongation, High Dk | UV adhesives |

Multifunctional Acrylate

| Product name | Structure                                                                                                                          | Functionality | Viscosity (cP @ 25℃ ) | Acid Value (mg KOH/g) | Characteristics                                                    | Applications                    |
|--------------|------------------------------------------------------------------------------------------------------------------------------------|---------------|-----------------------|-----------------------|--------------------------------------------------------------------|---------------------------------|
| DAC001       | <br>R = OH or CO <sub>2</sub> H<br>A = Acrylate | ≥ 5           | 42.5 ± 4              | 14.5 ~ 18             | Alkaline-soluble, High mechanical strength, High photo sensitivity | UV ink, UV-coating, Photoresist |

Silane-containing Acrylate

| Product name | Structure                                                                                                                                                            | Functionality | Viscosity (cP @ 25℃ ) | Characteristics               | Applications                       |
|--------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------|-----------------------|-------------------------------|------------------------------------|
| DAS001       | <br>R: H or C <sub>2</sub> H <sub>5</sub> O or Si(OCH <sub>3</sub> ) <sub>3</sub> | 140 ~ 180     | 7.2                   | High adhesion, High toughness | UV coating, photoresist, adhesives |

Alkaline-soluble Acrylate

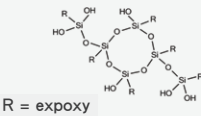
| Product name | Structure                                                                                                | Functionality | Viscosity (cP @ 25℃ ) | Characteristics                          | Applications            |
|--------------|----------------------------------------------------------------------------------------------------------|---------------|-----------------------|------------------------------------------|-------------------------|
| DAE001       | <br>OH or acid groups | 560-600       | 22 ± 4                | High thermal stability, Alkaline-soluble | UV coating, photoresist |

Modified Siloxane

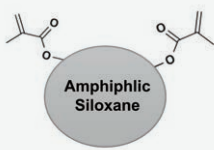
With its expertise in side-chain design and synthesis approaches, Daxin has developed several modified-siloxane products, including epoxy-modified siloxane and acrylate-modified siloxane, with thermal/UV curable abilities. In addition, special structures introduced in the side chain provides siloxane-based materials unique features, such as flexibility, low shrinkage, amphiphilicity…etc., that make them good candidates for special requirements. The potential applications for these modified siloxanes are sealant, hardener for coating, silicone hydrogel…etc.



Epoxy-modified Siloxane

| Product name | Structure                                                                                         | Functionality | EEW (g/eg) | (cP @ 25℃ ) | Characteristics                                 | Applications            |
|--------------|---------------------------------------------------------------------------------------------------|---------------|------------|-------------|-------------------------------------------------|-------------------------|
| DSE002       | <br>R = epoxy | 1             | 178        | 40 ± 10     | High thermal stability, low shrinkage, hardness | Thermal curing hardcoat |

Acrylate-modified Siloxane

| Product name | Structure                                                                                                     | Functionality | (cP @ 25℃ ) | Characteristics                    | Applications                |
|--------------|---------------------------------------------------------------------------------------------------------------|---------------|-------------|------------------------------------|-----------------------------|
| DSA001       | <br>Amphiphilic Siloxane | 2             | 40,000      | UV/thermal curable, amphiphilicity | Silicone hydrogel, coating, |

High-Purity Polymer

With the ability of polymer synthesis, precision manufacturing and purification technologies, Daxin can provide the polymers used in photoresists. Our high purity polymers can meet the requirements of well-controlled Mw (molecular weight) /PDI(polymer dispersity index) /copolymer ratio and low metal content. Powder and solution form are both available.

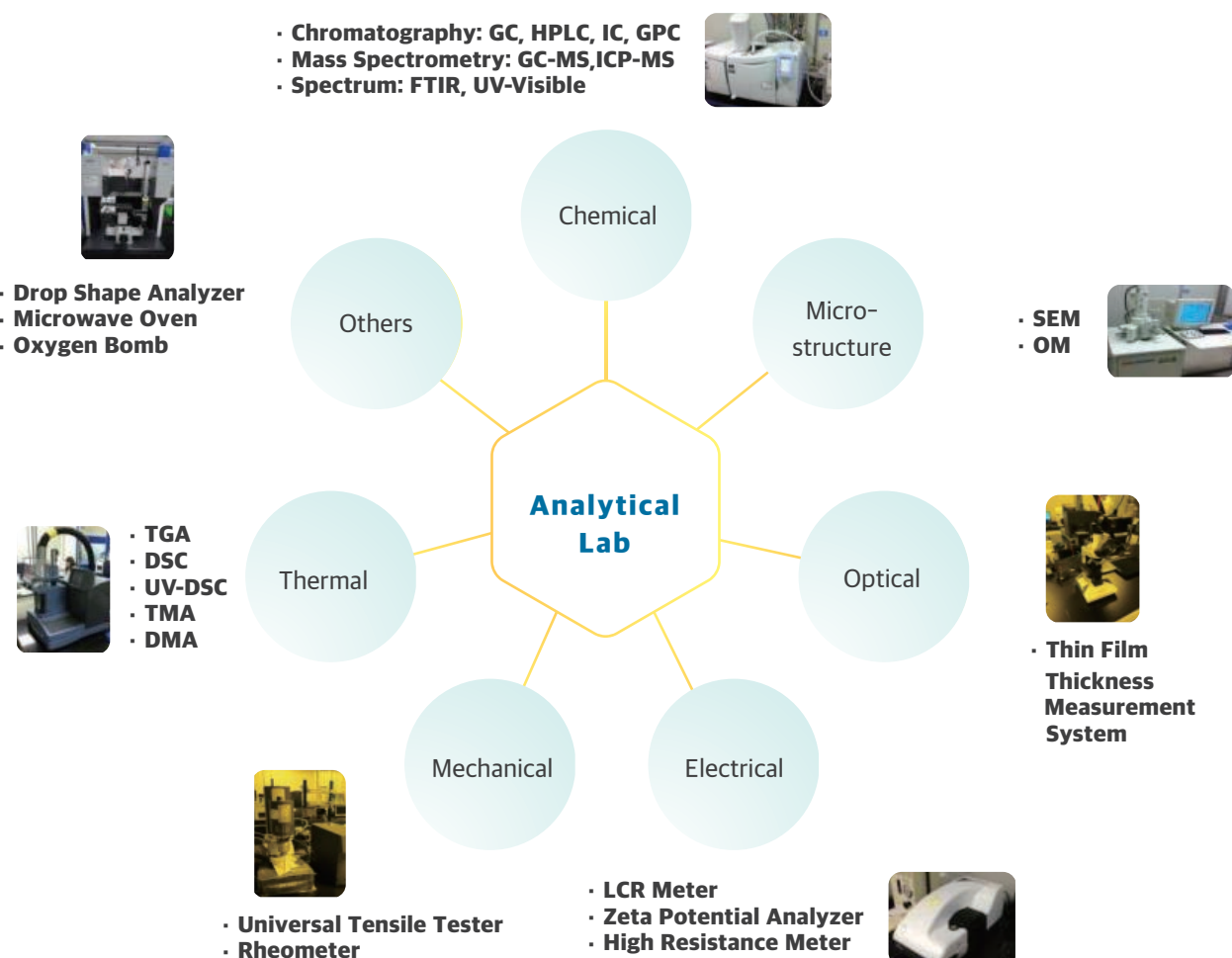
## Instrument Analysis

### Development and Improvement of Analytical Techniques and Testing Equipment

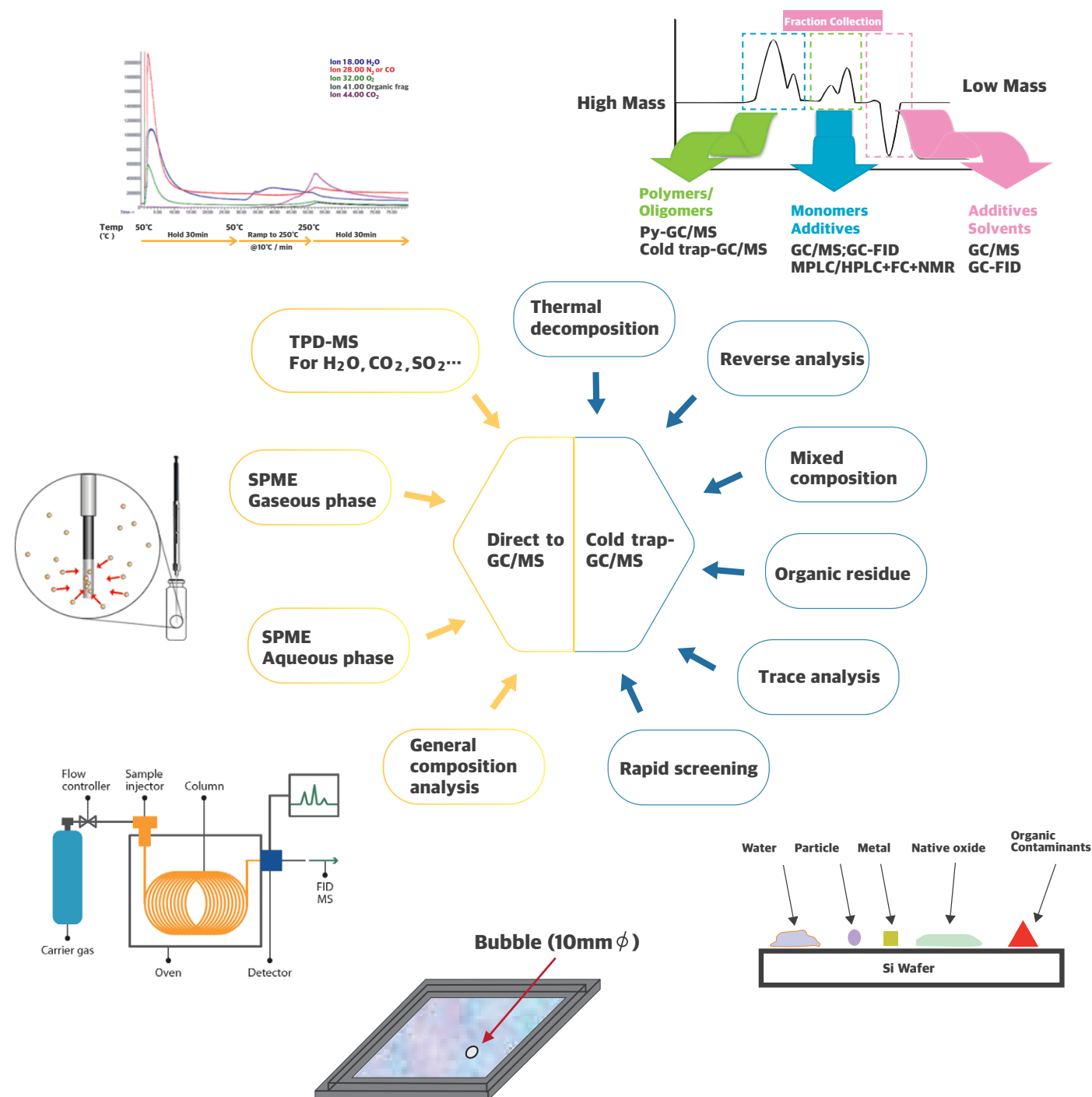
- Cold trap-GC/MS (Ex. Evolved Gas Analysis and Thermal Desorption Analysis)
- Development of testing method for the thermal expansion coefficient of transparent material film
- Development of technology on the rate of development of thin film material
- Modifications of variable temperature testing

### Identification of Chemical Composition

- Separation and purification of mixtures
- Composition identification
- Product failure mode analysis
- Identification of impurities and source tracking
- Product efficacy difference analysismaterial



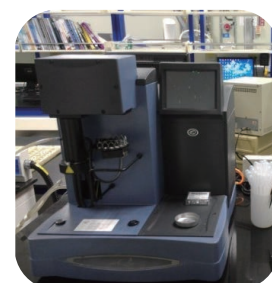
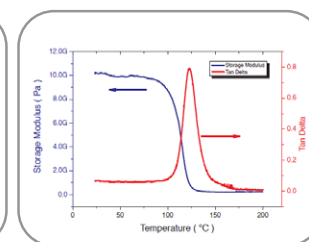
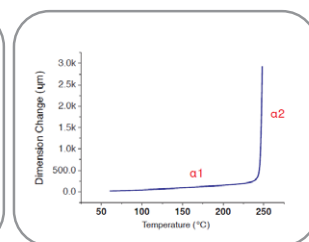
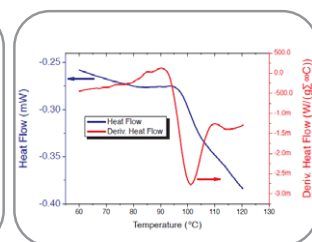
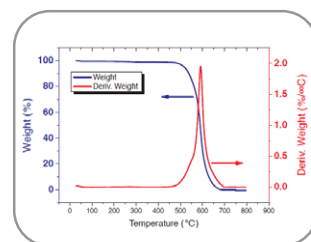
### Organic Components/Outgas Analysis



## Thermal Analysis

Physical parameter varies with temperature, time, and environment

| TGA                                                                                                                                                        | DSC                                                                                                                                                                                          | TMA                                                                                                                                                | DMA                                                                                                  |
|------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------|
| Weight change                                                                                                                                              | An endothermic or exothermic change                                                                                                                                                          | Dimension change                                                                                                                                   | The response to obtain phase angle and deformation data as applying a stress or strain the sample    |
| <ul style="list-style-type: none"> <li>Decomposition temperature (<math>T_d</math>)</li> <li>Composition information</li> <li>Thermal stability</li> </ul> | <ul style="list-style-type: none"> <li>Glass transition temperature</li> <li>Melting temperature</li> <li>Crystallization temperature</li> <li>Endothermic or exothermic reaction</li> </ul> | <ul style="list-style-type: none"> <li>Thermal expansion coefficient</li> <li>Glass transition temperature</li> <li>Melting temperature</li> </ul> | <ul style="list-style-type: none"> <li>Change with temperature while under dynamic stress</li> </ul> |

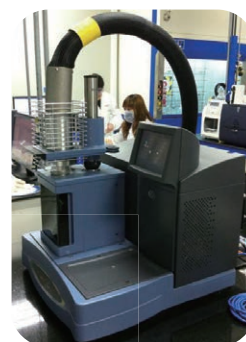


### TA TGA

Model: Q500

Applications:

1. Weight loss analysis
2. Thermal stability analysis
3. General composition analysis



### TA TMA

Model: Q400 EM

Applications:

1. CTE
2. Strain & stress
3. Creep analysis



### TA DSC

Model: Q200 & Q2000

Applications:

1. Phase transition temperature ( $T_m, T_g, T_c$ )
2. Heat of reaction
3. Specific heat capacity
4. Compatible with UV-light

# DAXiN

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